

S/N Unknown

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Martin Ceredig Roberts et al. Examiner: Unknown
Serial No.: Unknown Group Art Unit: Unknown
Filed: Herewith Docket: 303.451US6
Title: METHOD FOR FORMING AN INTEGRATED CIRCUIT INTERCONNECT
USING A DUAL POLY PROCESS

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PATENT

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INFORMATION DISCLOSURE STATEMENT

Box Patent Application
Commissioner for Patents
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for review in connection with the above-identified patent application. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner be returned to the Applicants.

In accordance with 37 C.F.R. § 1.98(d), copies of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 09/351,884, filed on July 13, 1999, which is relied upon for an earlier filing date under 35 U.S.C. § 120.

Applicants respectfully request consideration of these references during prosecution of the above-identified matter. The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

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By their Representatives,

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Date of Deposit: December 21, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.